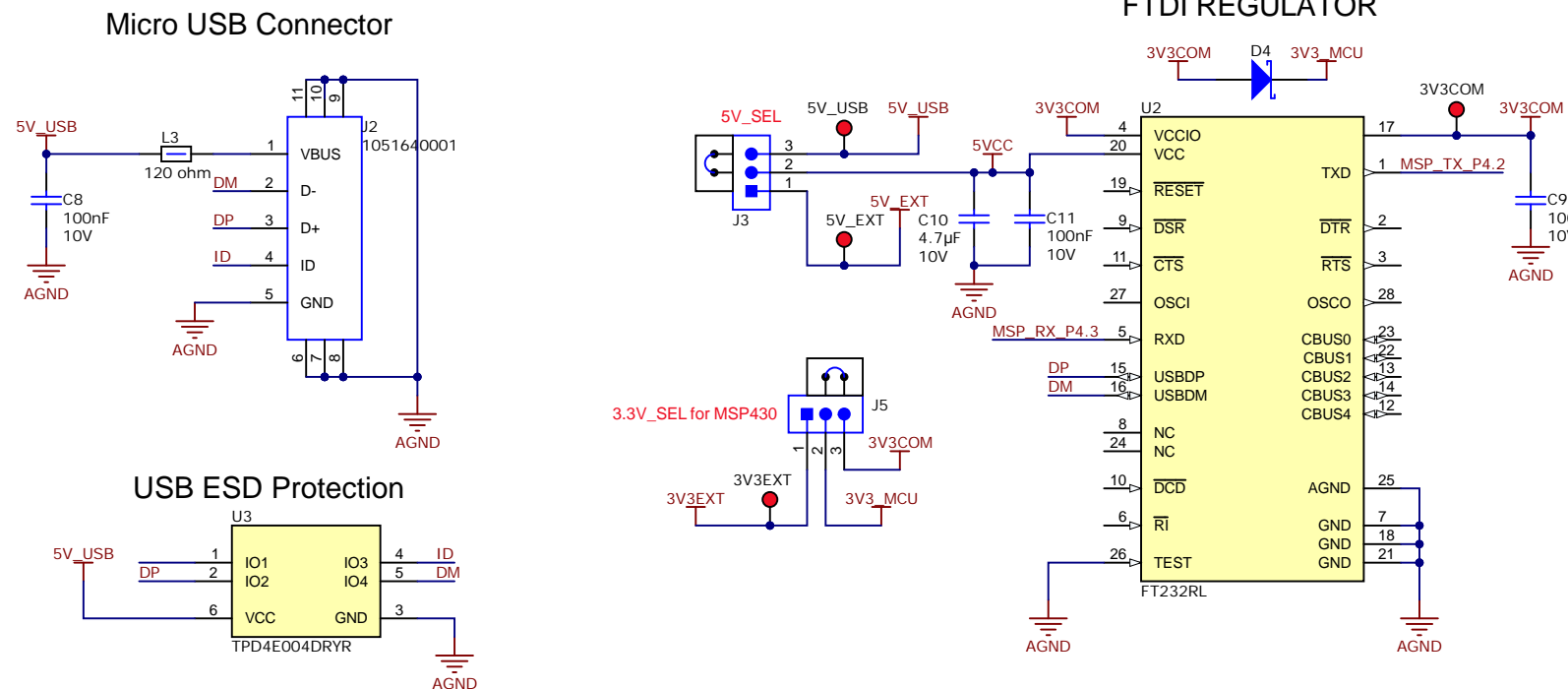
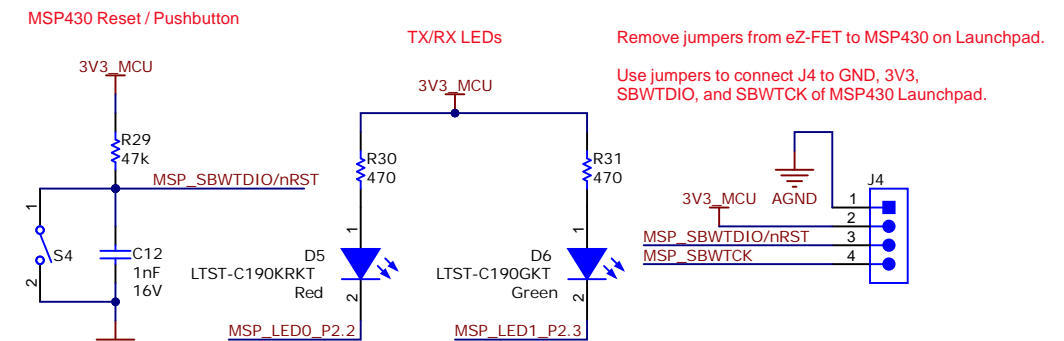


FTDI

FTDI REGULATOR



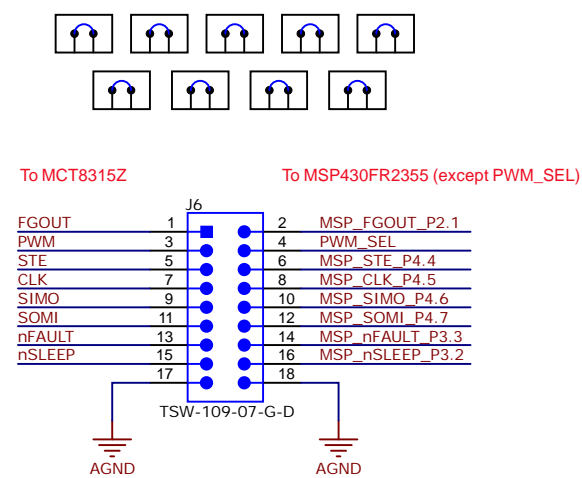
MCU PROGRAMMING



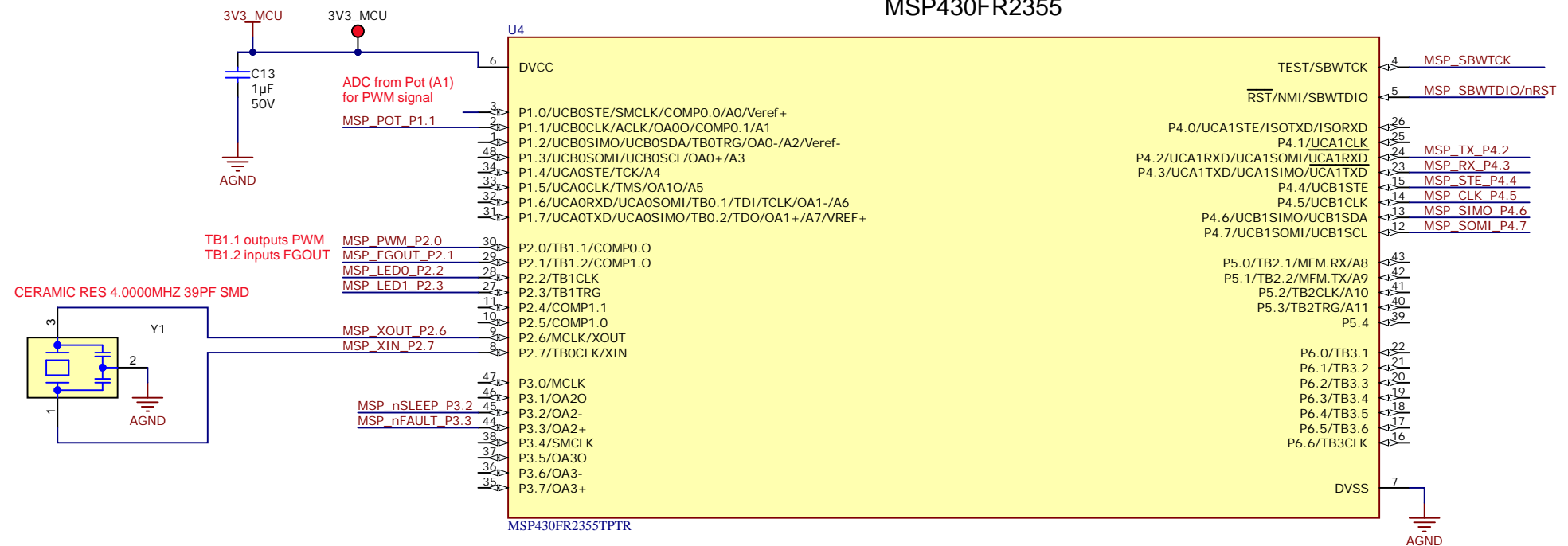
MSP430FR2355IPT

MSP430FR2355

Signal Bank for connecting MSP430 + MCT8315Z



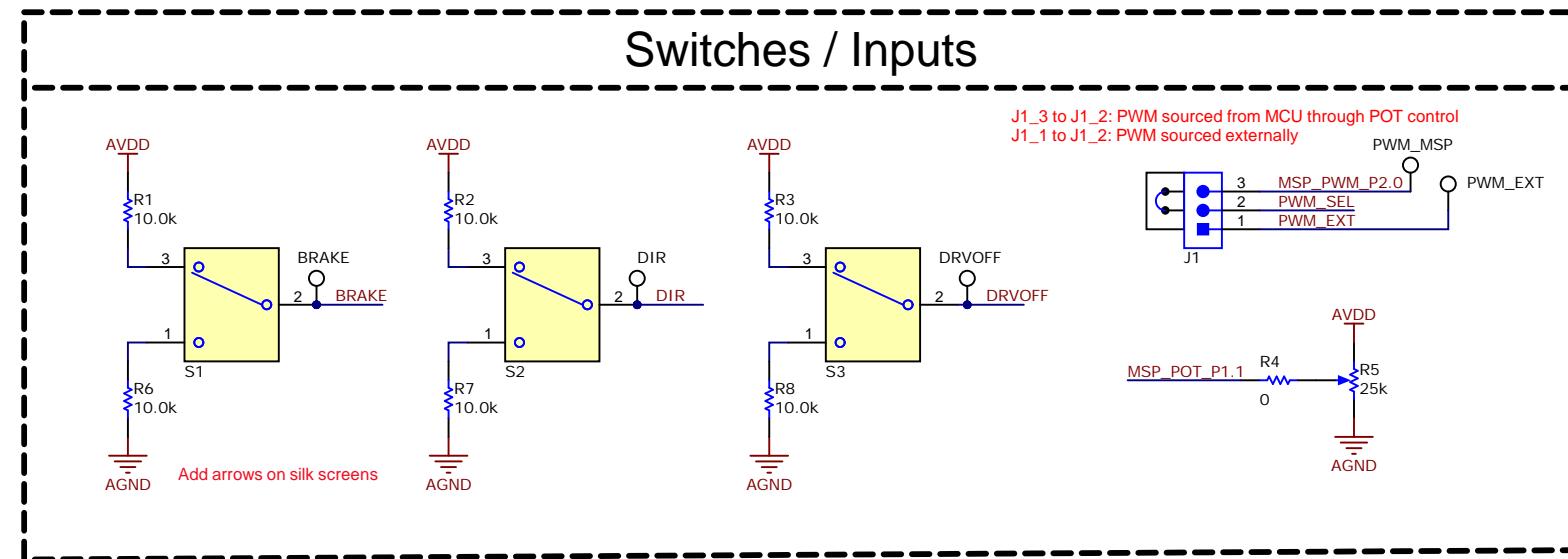
Populate jumpers to communicate onboard MSP430FR2355 to the MCT8315Z or depopulate jumpers to use standalone MSP430 or MCT8315Z.




Orderable: MCT8315ZEV	Designed for: Public Release	Mod. Date: 9/8/2023
TID #: N/A	Project Title: MCT8315ZEV	
Number: MD079	Rev: A	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 1 of 5
Drawn By:	File: MD079_INTERFACE.SchDoc	Size: B
Engineer: Hong Ze Khor	Contact: http://www.ti.com/support	



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Orderable: MCT83152EVM	Designed for: Public Release	Mod. Date: 8/22/2023	
TID #: N/A	Project Title: MCT83152EVM		
Number: MD079	Rev: A	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 2 of 5	
Drawn By:	File: MD079_CONTROL_SchDoc	Size: B	
Engineer: Hong Ze Khor	Contact: http://www.ti.com/support		http://www.ti.com © Texas Instruments 2023

[illegible]

CONNECTORS & INTERFACE

Motor Output

J8
3 OUTC
2 OUTB
1 OUTA
MOTOR_OUT

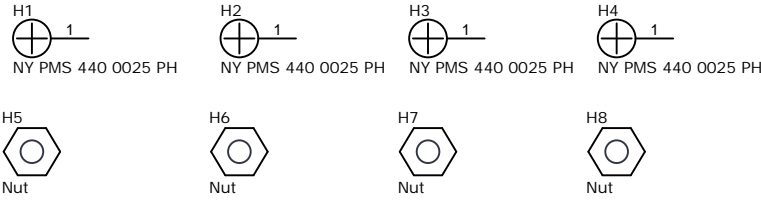
Hall Connections

AVDD AVDD AVDD
R34 10.0k R35 10.0k R36 10.0k
J9 J10 J11
HNC HPC HNB HPB HNA HPA
Optional filtering caps
C23 = 100nF 16V
C24 = 100nF 16V
C25 = 100nF 16V
Connector for Hall sensors
J12
8 HNC
7 HPC
6 HNB
5 HPB
4 HNA
3 HPA
2 HPA
1 AGND
HALL_PWR
HALL_EXT
HALL_PWR_SEL
VBK

Digital (single-ended): connect hall sensors to only HPx, install pullup jumpers J9-J11
Analog (differential): connect hall elements to HPx and HNx, remove pullup J9-J11

Grounding

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PCB Number: MD079
PCB Rev: A

PCB
LOGO
Texas Instruments



PCB
LOGO
FCC disclaimer

PCB
LOGO
WEEE logo

LBL1
PCB Label
THT-14-423-10



CAUTION HOT SURFACE



CAUTION HOT SURFACE

Variant/Label Table	
Variant	Label Text
001	MCT8315ZEVMSPI
002	MCT8315ZEVMSHW
003	MCT8315ZEVMSHW, NO BUCK

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: MCT8315ZEVMS		Designed for: Public Release	Mod. Date: 11/1/2023
TID #: N/A		Project Title: MCT8315ZEVMS	
Number: MD079	Rev: A	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001		Sheet: 5 of 5
Drawn By:	File: MD079_HARDWARE.SchDoc		Size: B
Engineer: Hong Ze Khor		Contact: http://www.ti.com/support	